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02060290

November 11, 2002

Securities and Exchange Commission  
Office of International Corporate Finance  
450 Fifth Street, N.W.  
Washington D.C. 20549

**SUPPL**

Re: Samsung Electronics Co., Ltd. – Rule 12g3-2(b) Filing, Commission File No. 82-3109

Ladies and Gentlemen:

The following information is provided by Samsung Electronics Co., Ltd. to the Securities and Exchange Commission pursuant to paragraph (b) (1) (i) of Rule 12g3-2(b) under the Securities Exchange Act of 1934, as amended.

Should you have any questions on the foregoing, please do not hesitate to call Jin Hyuk Park of Simpson Thacher & Bartlett, U.S. counsel to Samsung Electronics Co., Ltd. at (852) 2514-7665. Thank you.

Very truly yours,

Daniel Kim

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## **SEC Develops MCP Bonder**

**November 11, 2002**

### Multi-MCP Bonder

- Enables more than two chips to be mounted on a single substrate using different bonding methods
- Shortens the MCP bonding process from 1.4 seconds to 1 second

SEC has developed the world's first Multi-Chip Package Bonder that uses both epoxy type and tape type bonding methods. The MCP Bonder was developed at the SEC Mechatronics Center. By using two bonding methods in mounting more than two chips (eight chips maximum) on a single substrate, the time needed in applying the epoxy molding compound between chips is reduced by 30% compared to that of other bonders.